BTA212B series D, E and F

GENERAL DESCRIPTION

QUICK REFERENCE DATA

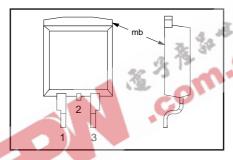
Passivated guaranteed commutation triacs in a plastic envelope suitable for surface mounting intended for use in motor control circuits or with other highly inductive loads. These devices balance the requirements of commutation performance and gate sensitivity. The "sensitive gate" E series and "logic level" D series are intended for interfacing with low power drivers, including micro controllers.

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
V _{DRM} I _{T(RMS)} I _{TSM}	BTA212B- BTA212B- BTA212B- Repetitive peak off-state voltages RMS on-state current Non-repetitive peak on-state current	600D 600E 600F 600 12 95	800E 800F 800 12 95	V A A

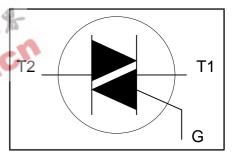
PINNING - SOT404

PIN	DESCRIPTION		
1	main terminal 1		
2	main terminal 2		
3	gate		
mb	main terminal 2		

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MA	X.	UNIT
V_{DRM}	Repetitive peak off-state voltages			-600 600 ¹	-800 800	V
I _{T(RMS)}	RMS on-state current	full sine wave;	-	12		Α
I _{TSM}	Non-repetitive peak on-state current	$T_{mb} \le 99$ °C full sine wave; $T_j = 25$ °C prior to surge t = 20 ms t = 16.7 ms	-	95 10		A A
l ² t dl _T /dt	l ² t for fusing Repetitive rate of rise of on-state current after	t = 10.7 m/s t = 10 ms $I_{TM} = 20 \text{ A}$; $I_G = 0.2 \text{ A}$; $dI_G/dt = 0.2 \text{ A}/\mu\text{s}$	-	45 10	5	A ² s A/μs
I _{GM} V _{GM} P _{GM} P _{G(AV)}	triggering Peak gate current Peak gate voltage Peak gate power Average gate power	over any 20 ms	-	2 5 5 0.9		A V W W
T_{stg} T_{j}	Storage temperature Operating junction temperature	poliou	-40 -	15 12		°C

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 $A/\mu s$.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{\text{th j-mb}}$ $R_{\text{th j-a}}$	Thermal resistance junction to mounting base Thermal resistance junction to ambient	full cycle half cycle in free air	- - -	- - 55	1.5 2.0 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.		MAX.		UNIT
		BTA212B-		D	D	Е	F	
I _{GT}	Gate trigger current ²	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ T2+ G+	-	1.0	5	10	25	mA
 I _L	Latching current	T2+ G- T2- G- V _D = 12 V; I _{GT} = 0.1 A	4.1	2.2 3.3	5 5	10 10	25 25	mA mA
		T2+ G+ T2+ G- T2- G-	表 30	6 6 9	15 25 25	25 30 30	30 40 40	mA mA mA
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	0.	3.8	15	25	30	mA
					D, E, F	=		<u> </u>
V_{T}	On-state voltage Gate trigger voltage	$I_T = 17 \text{ A}$ $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ $V_D = 400 \text{ V}; I_T = 0.1 \text{ A};$	- - 0.25	1.3 0.7 0.4		1.6 1.5 -		V V V
I _D	Off-state leakage current	$T_j = 125 ^{\circ}\text{C}$ $V_D = V_{DRM(max)};$ $T_j = 125 ^{\circ}\text{C}$	-	0.1		0.5		mA

DYNAMIC CHARACTERISTICS

 $T_j = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		TYP.	MAX.	UNIT
		BTA212B-	D	E	F	D		
dV _D /dt	Critical rate of rise of off-state voltage	V _{DM} = 67% V _{DRM(max)} ; T _j = 110 °C; exponential waveform; gate open circuit	20	60	70	30	-	V/μs
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 110 ^{\circ}\text{C};$ $I_{T(RMS)} = 12 \text{ A};$ $dV_{com}/dt = 20 \text{V}/\mu\text{s}; \text{ gate}$ open circuit	1.8	3.5	5	3	-	A/ms
dI _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 110 ^{\circ}\text{C};$ $I_{T(RMS)} = 12 \text{ A};$ $dV_{com}/dt = 0.1 \text{V}/\mu\text{s}; \text{ gate}$ open circuit	5	16	19	100	-	A/ms
			D, E, F					
t _{gt}	Gate controlled turn-on time	$I_{TM} = 12 \text{ A}; V_D = V_{DRM(max)};$ $I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A/}\mu\text{s}$	-	-	-	2	-	μs

² Device does not trigger in the T2-, G+ quadrant.

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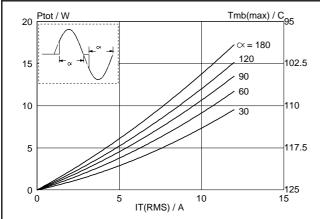


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where $\alpha =$ conduction angle.

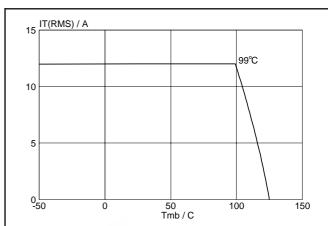


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

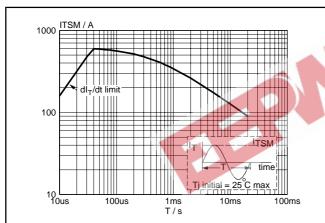


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

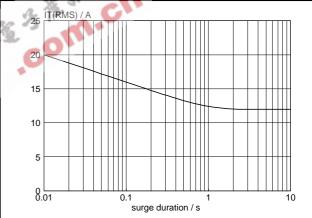


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \le 99$ °C.

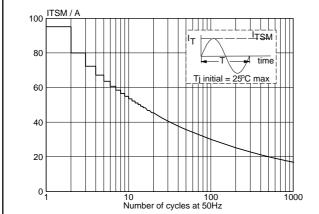


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

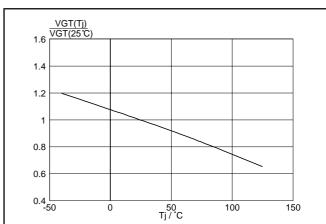
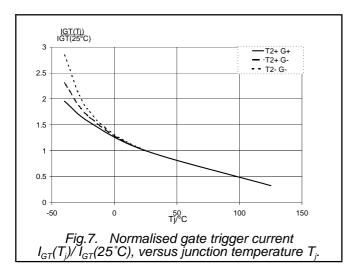


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_{j} .

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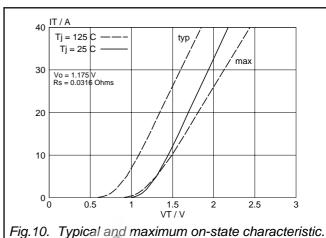
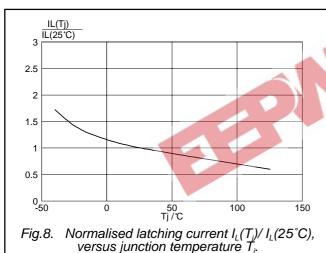
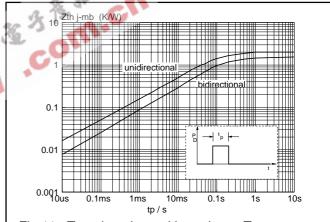


Fig. 10. Typical and maximum on-state characteristic.





IH(Tj) 3 IH(25°C) 0.5 0 -50 50 Tj /℃ 150 Fig.9. Normalised holding current $I_H(T_i)/I_H(25^{\circ}\text{C})$, versus junction temperature T_j .

Fig.11. Transient thermal impedance $Z_{th j-mb}$, versus pulse width $t_{\rm p}$

- FTYPE - FTYPE

dlcom/dt (A/ms)

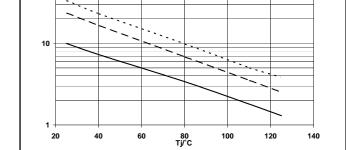
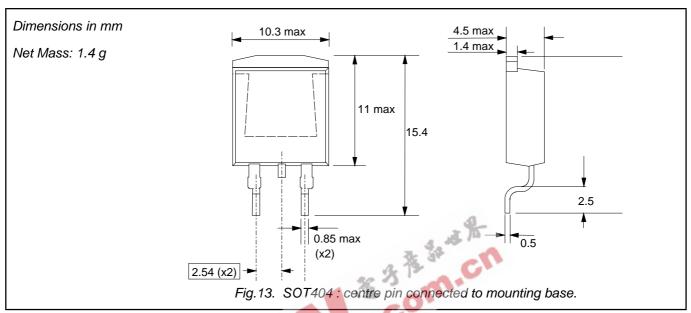


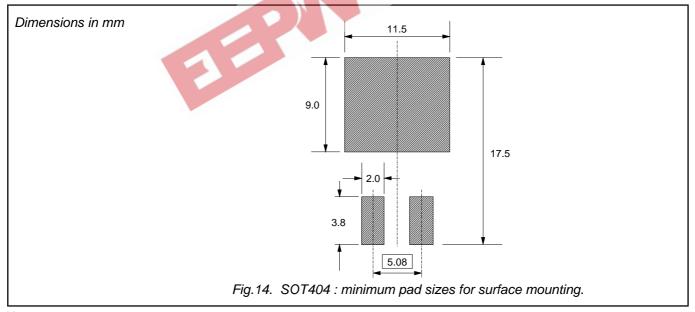
Fig.12. Minimum, critical rate of change of commutating current dI_{com}/dt versus junction temperature, $dV_{com}/dt = 20V/\mu s$.

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MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

1. Plastic meets UL94 V0 at 1/8".

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DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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